

**AMENDED CLAIMS**

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original claim 12 replaced by amended claims 13 (1 page) ]

13. A method according to claim 10, claim 11 or claim 12 in which there are a plurality of said integrated circuits, the plate extending between each of the integrated circuits and the substrate, the method further including a singulation step in which the substrate and plate are cut to produce a plurality  
5 of semiconductor packages each including at least one of the integrated circuits.